

ABSTRACT OF THE DISCLOSURE

The present invention discloses a curable composition that is controllably curable by microwave energy. More particularly, this invention discloses a heat curable composition that is controllably curable by microwave energy including at least one heat curable resin
5 component, microwave absorbable particles in an amount of about 10% by weight of said composition and at least one curing agent for the heat curable resin component. A method of controllably curing a composition that includes the inventive composition is also contemplated.

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